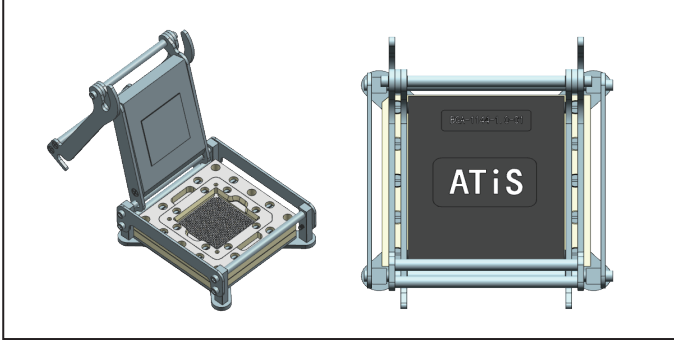


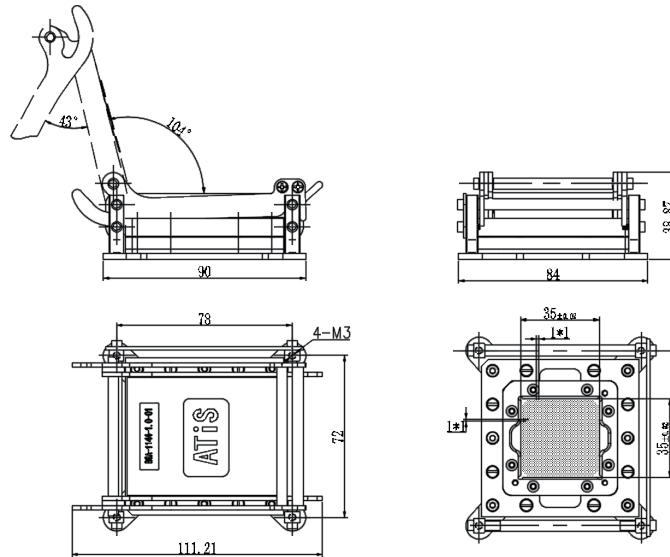
# BGA BALL GRID ARRAY

## BGA-1144-1.0-01



- 材质/Material  
主体/Body: PEEK  
接触/Contact: Pogopin  
镀覆/Plating: Au plating (Ni-base)
- 电特性/Electrical Characteristics  
额定电流/Rated Current: 3A  
绝缘电阻/Insulation Resistance: 100mΩ min. at 500V DC  
接触电阻/Contact Resistance: 100mΩ max. at 100mA max
- 其他/Others  
使用温度/Operating Temperature Range: -55°C~+175°C  
抗疲劳/Anti-Fatigue: 50000 cycle (因测试条件不同结果可能不同/Results may vary depending on test conditions)

产品尺寸/Product Dimensions: (长宽高/LWH, 关键封装尺寸/Critical Package Sizes, 引脚尺寸/Pin Size)



器件封装要求含/Device Packaging Requirements Including

